Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the above-identified application.

Listing of Claims

1.   (Previously Presented) A method comprising:

forming a tungsten plug in a dielectric layer;

forming an electrically conductive interconnect line on the dielectric layer after formation of the tungsten plug, wherein the tungsten plug is electrically connected to the electrically conductive interconnect line;

contacting the electrically conductive interconnect line with liquid water after formation of the electrically conductive interconnect line;

contacting the electrically conductive interconnect line with a solution to remove residual polymer after the electrically conductive interconnect line is contacted with the liquid water;

wherein the electrically conductive interconnect line is contacted with the liquid water for less than 120 minutes.

2.   (Previously Presented) The method of claim 1 wherein the liquid water is degasified and deionized.

3.   (Previously Presented) The method of claim 1 wherein the liquid water is deionized but not degasified.

4.   (Previously Presented) The method of claim 1 wherein the liquid water is degasified but not deionized.

5.   (Previously Presented) The method of claim 1 wherein the liquid water is neither degasified nor deionized.

6.   (Previously Presented) The method of claim 1 wherein the liquid water has a pH that is at or near neutral.

7.   (Previously Presented) The method of claim 1 wherein the electrically conductive interconnect line is contacted with the liquid water for less than 60 minutes.

8.   (Previously Presented) The method of claim 1 wherein the electrically conductive interconnect line is contacted with the liquid water for less than 15 minutes.

9.   (Original) The method of claim 1 wherein the electrically conductive interconnect line is formed from a metal stack that includes one or more of titanium, titanium nitride, aluminum, an aluminum copper alloy, and an aluminum silicon copper alloy.

10. - 26.   (Canceled).

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